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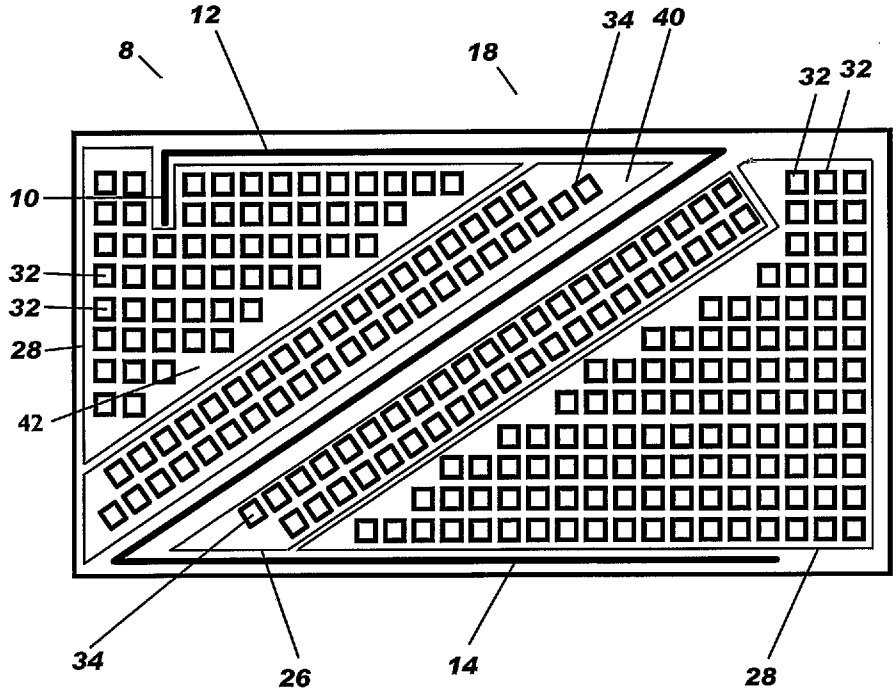
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(54) Title: IC TILING PATTERN METHOD, IC SO FORMED AND ANALYSIS METHOD



(57) Abstract: The invention provides a method for providing an integrated circuit (6) having a substantially uniform density between parts (10, 12, 14, and 16) of the IC that are nonorthogonally angled. In particular, the invention provides fill tiling patterns (32, 34) oriented substantially parallel to electrical structure regardless of their angle. A method of electrical analysis based on this provision is also provided as is a related program product.

WO 2004/059732 A1

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